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Vishay Semiconductors

AUTOMOTIVE

HALOGEN

FREE

GREEN

High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology



LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

As part of the <u>SurfLight</u>TM portfolio, the VSMY2943 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

Package type: surface-mountPackage form: GW, RGW



AEC-Q101 qualified

• Peak wavelength: $\lambda_p = 940 \text{ nm}$

· High reliability

· High radiant power

· Very high radiant intensity

• Angle of half intensity: $\varphi = \pm 28^{\circ}$

• Suitable for high pulse current operation

· Terminal configurations: gullwing or reverse gullwing

Package matches with detector VEMD2503X01 series

• Floor life: 4 weeks, MSL 2a, acc. J-STD-020

 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Automotive sensors
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination
- Head-up displays

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (°)	$λ_{p}$ (nm)	t _r (ns)	
VSMY2943RGX01	50	± 28	940	10	
VSMY2943GX01	50	± 28	940	10	

Note

· Test conditions see table "Basic Characteristics"

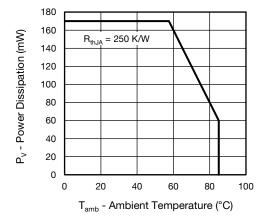
ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMY2943RGX01z	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing	
VSMY2943GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing	

Note

• MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	Α
Power dissipation		P _V	180	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	According to Fig. 7, J-STD-020	T _{sd}	260	°C
Thermal resistance junction to ambient	J-STD-051, soldered on PCB	R _{thJA}	250	K/W



100 R_{th,JA} = 250 K/W

80 R_{th,JA} = 250 K/W

40 0 20 40 60 80 100

T_{amb} - Ambient Temperature (°C)

Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.4	1.8	V
	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	V _F	-	2.5	-	V
Temperature coefficient of V _F	I _F = 100 mA	TK _{VF}	-	-0.7	-	mV/K
Reverse current		I _R	Not designed for reverse operation		se operation	μA
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ	-	55	-	pF
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	27	50	75	mW/sr
	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e	-	350	-	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	φ _e	-	55	-	mW
Temperature coefficient of radiant power	I _F = 100 mA	ТКφ _е	-	-0.2	-	%/K
Angle of half intensity		φ	-	± 28	-	0
Peak wavelength	I _F = 100 mA	λ_{p}	920	940	960	nm
Spectral bandwidth	I _F = 100 mA	Δλ	-	50	-	nm
Temperature coefficient of λ _p	I _F = 100 mA	TKλ _p	-	0.25	-	nm/K
Rise time	I _F = 100 mA, 10 % to 90 %	t _r	-	10	-	ns
Fall time	I _F = 100 mA, 10 % to 90 %	t _f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

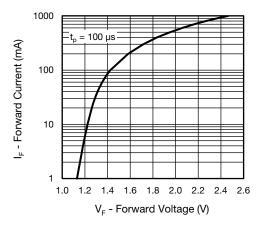


Fig. 3 - Forward Current vs. Forward Voltage

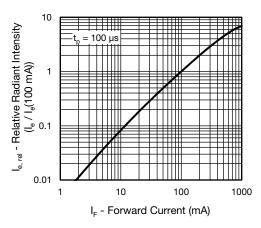


Fig. 4 - Radiant Intensity vs. Forward Current

300 255 250 240 °C 200 Temperature (°C) Max. 30 s 150 Max. 100 s Max. 120 s 100 Max. ramp down 6 °C/s Max. ramp up 3 °C/s 50 50 100 150 200 250 Time (s) 19841-1

SOLDER PROFILE

Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

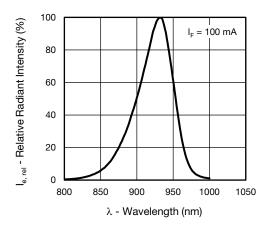


Fig. 5 - Relative Radiant Power vs. Wavelength

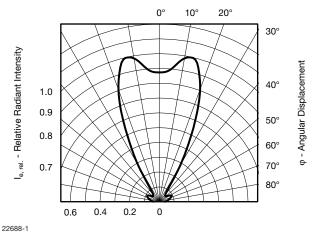


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

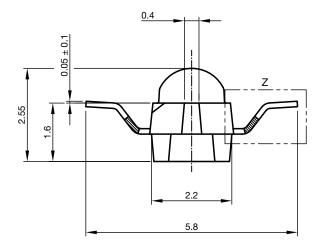
Conditions: T_{amb} < 30 °C, RH < 60 %

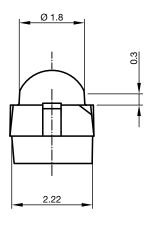
Moisture sensitivity level 2a, acc. to J-STD-020.

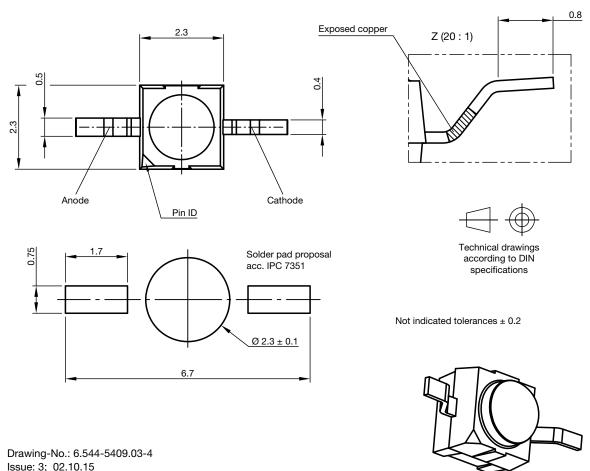
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters: VSMY2943RGX01



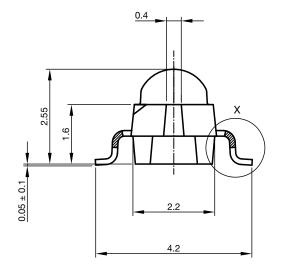


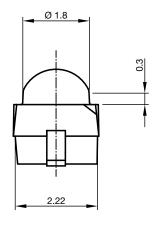


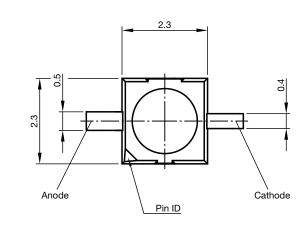
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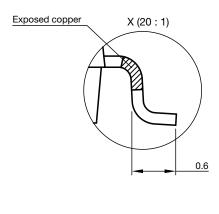
Rev. 1.2, 02-Apr-2025 4 Document Number: 84891

PACKAGE DIMENSIONS in millimeters: VSMY2943GX01



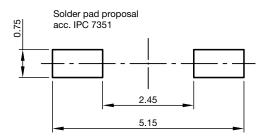




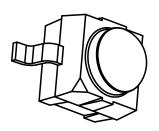




Technical drawings according to DIN specifications



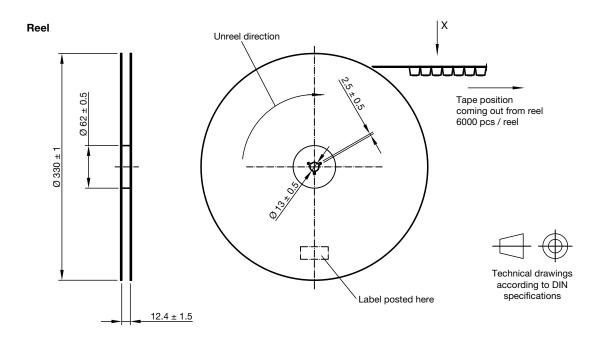
Not indicated tolerances ± 0.2



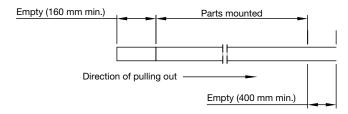
Drawing-No.: 6.544-5408.03-4

Issue: 3; 02.10.15

TAPING AND REEL DIMENSIONS in millimeters: VSMY2943RGX01



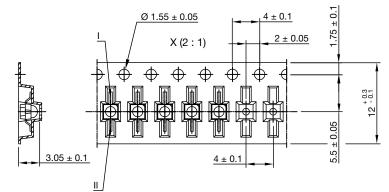
Leader and trailer tape



Terminal position in tape

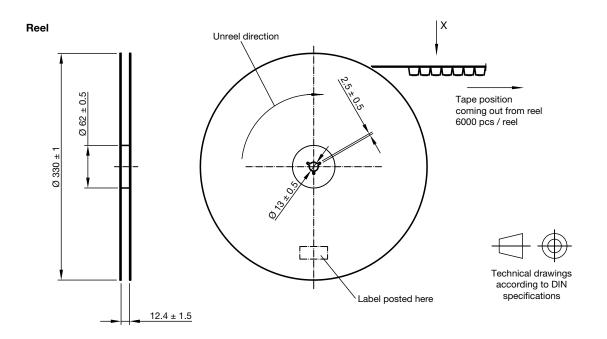
Device	Lead I	Lead II	
VSMB2943RGX01			
VSMF2893RGX01	Cathode	Anode	
VEMD2x03X01			
VEMT2x03X01	Collector	Emitter	
VSMY2xxx	Anode	Cathode	

Drawing-No.: 9.800-5100.02-4 Issue: prel.; 11.07.19

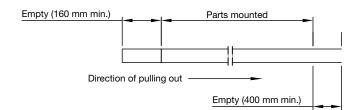




TAPING AND REEL DIMENSIONS in millimeters: VSMY2943GX01



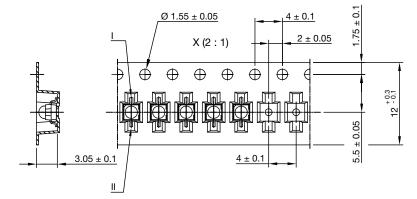
Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II	
VSMB2943GX01			
VSMF2893GX01	Cathode	Anode	
VEMD2x23X01			
VEMT2x23X01	Collector	Emitter	
VSMY2xxx	Anode	Cathode	

Drawing-No.: 9.800-5091.21-4 Issue: prel.; 11.07.19





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